

200 kPa On-Chip Temperature Compensated and Calibrated Silicon Pressure Sensors

The MPMZ2202 device is a silicon piezoresistive pressure sensor providing a highly accurate and linear voltage output directly proportional to the applied pressure. The sensor is a single, monolithic silicon diaphragm with the strain gauge and a thin-film resistor network integrated on-chip. The chip is laser trimmed for precise span and offset calibration and temperature compensation.

Features

- Temperature Compensated Over 0°C to +85°C
- Available in Easy-to-Use Tape and Reel
- Ratiometric to Supply Voltage
- Gauge Ported and Non Ported Options
- Increased media compatibility fluorocarbon gel

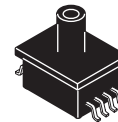
Typical Applications

- Pump/Motor Controllers
- Robotics
- Level Indicators
- Medical Diagnostics
- Pressure Switching
- Barometers
- Altimeters

**MPMZ2202
 SERIES**

**COMPENSATED AND CALIBRATED
 PRESSURE SENSOR
 0 TO 200 kPa (0 TO 29 psi)
 40 mV FULL SCALE SPAN
 (TYPICAL)**

MPAK PACKAGE



**MPMZ2202GS
 CASE 1320A-02**

ORDERING INFORMATION

| Device Type | Options | Case No. | MPX Series Order No. | Packing Options | Device Marking |
|-------------|-------------------|----------|----------------------|-----------------|----------------|
| Ported | Gauge, Axial Port | 1320A | MPMZ2202GS | Rails | MPMZ2202GS |
| | Gauge, Axial Port | 1320A | MPMZ2202GST1 | Tape & Reel | MPMZ2202GS |

PIN NUMBER

| | | | |
|---|-------------------|---|-------------------|
| 1 | GND | 3 | V _S |
| 2 | +V _{OUT} | 4 | -V _{OUT} |

Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

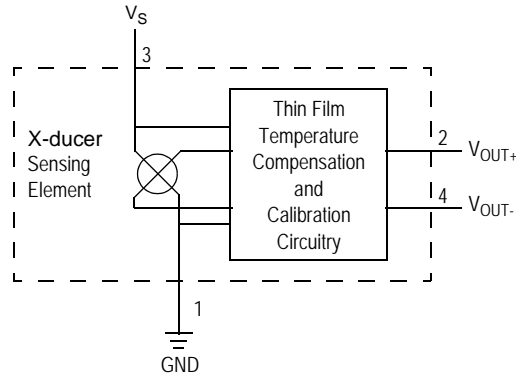


Figure 1. Temperature Compensated Pressure Sensor Schematic

VOLTAGE OUTPUT VERSUS APPLIED DIFFERENTIAL PRESSURE

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side relative to the vacuum side. Similarly, output voltage increases as increasing vacuum is applied to the vacuum side relative to the pressure side.

Table 1. Maximum Ratings⁽¹⁾

| Rating | Symbol | Value | Unit |
|-----------------------|-----------|-------------|------|
| Maximum Pressure | P_{max} | 400 | kPa |
| Storage Temperature | T_{stg} | -40 to +125 | °C |
| Operating Temperature | T_A | -40 to +125 | °C |

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Table 2. Operating Characteristics ($V_S = 10 \text{ Vdc}$, $T_A = 25^\circ\text{C}$.)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|---------------------------------|------|-----------|------|-------------|
| Pressure Range ⁽¹⁾ | P_{OP} | 0 | — | 200 | kPa |
| Supply Voltage ⁽²⁾ | V_S | — | 10 | 16 | Vdc |
| Supply Current | I_O | — | 6.0 | — | mAdc |
| Full Scale Span ⁽³⁾ | V_{FSS} | 38.5 | 40 | 41.5 | mV |
| Offset ⁽⁴⁾ | MPMZ2202D/G Series V_{OFF} | -1.0 | — | 1.0 | mV |
| Sensitivity | $\Delta V/\Delta P$ | — | 0.2 | — | mV/kPa |
| Linearity ⁽⁵⁾ | MPMZ2202D/G Series | — | -0.6 | — | % V_{FSS} |
| Pressure Hysteresis ⁽⁵⁾ (0 to 100 kPa) | — | — | ± 0.1 | — | % V_{FSS} |
| Temperature Hysteresis ⁽⁵⁾ (-40°C to +125°C) | — | — | ± 0.5 | — | % V_{FSS} |
| Temperature Effect on Full Scale Span ⁽⁵⁾ | TCV_{FSS} | -2.0 | — | 2.0 | % V_{FSS} |
| Temperature Effect on Offset ⁽⁵⁾ | TCV_{OFF} | -1.0 | — | 1.0 | mV |
| Input Impedance | Z_{IN} | 1000 | — | 2500 | Ω |
| Output Impedance | Z_{OUT} | 1400 | — | 3000 | Ω |
| Response Time ⁽⁶⁾ (10% to 90%) | t_R | — | 1.0 | — | ms |
| Warm-Up | — | — | 20 | — | ms |
| Offset Stability ⁽⁷⁾ | — | — | ± 0.5 | — | % V_{FSS} |

1. 1.0 kPa (kiloPascal) equals 0.145 psi.

2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.

3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

4. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.

5. Accuracy (error budget) consists of the following:

- Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.
- Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
- Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
- TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85°C, relative to 25°C.
- TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.

6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{OUT} = V_{OFF} + \text{sensitivity} \times P$ over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 2) or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. The

specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

Operating characteristics, internal reliability and qualification tests are based on use of dry clean air as the pressure media. Media other than dry clean air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.

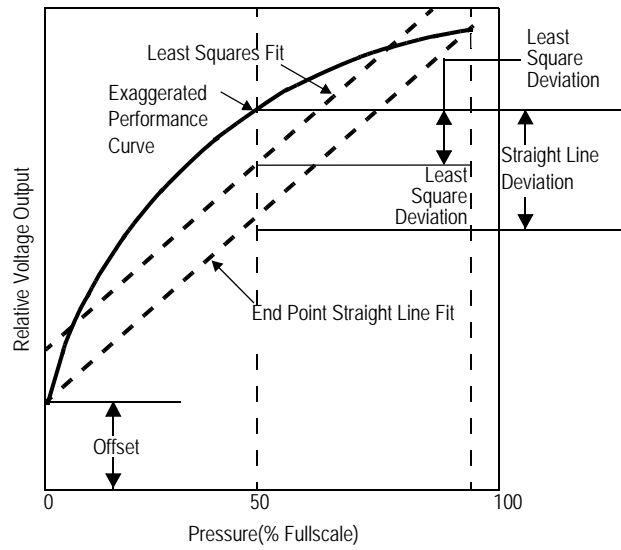


Figure 2. Linearity Specification Comparison

ON-CHIP TEMPERATURE COMPENSATION AND CALIBRATION

Figure 3 shows the minimum, maximum and typical output characteristics of the MPMZ2202 series at 25°C. The output

is directly proportional to the differential pressure and is essentially a straight line.

A gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

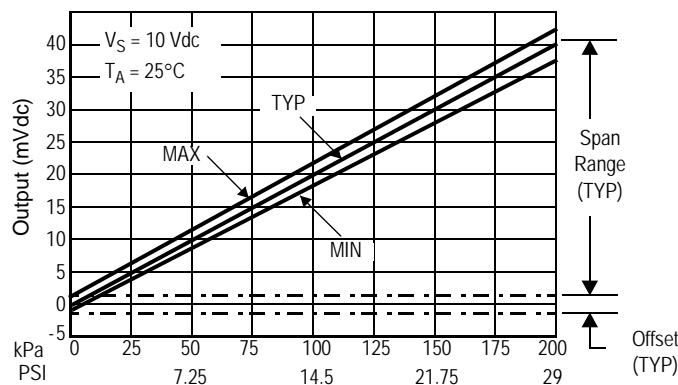
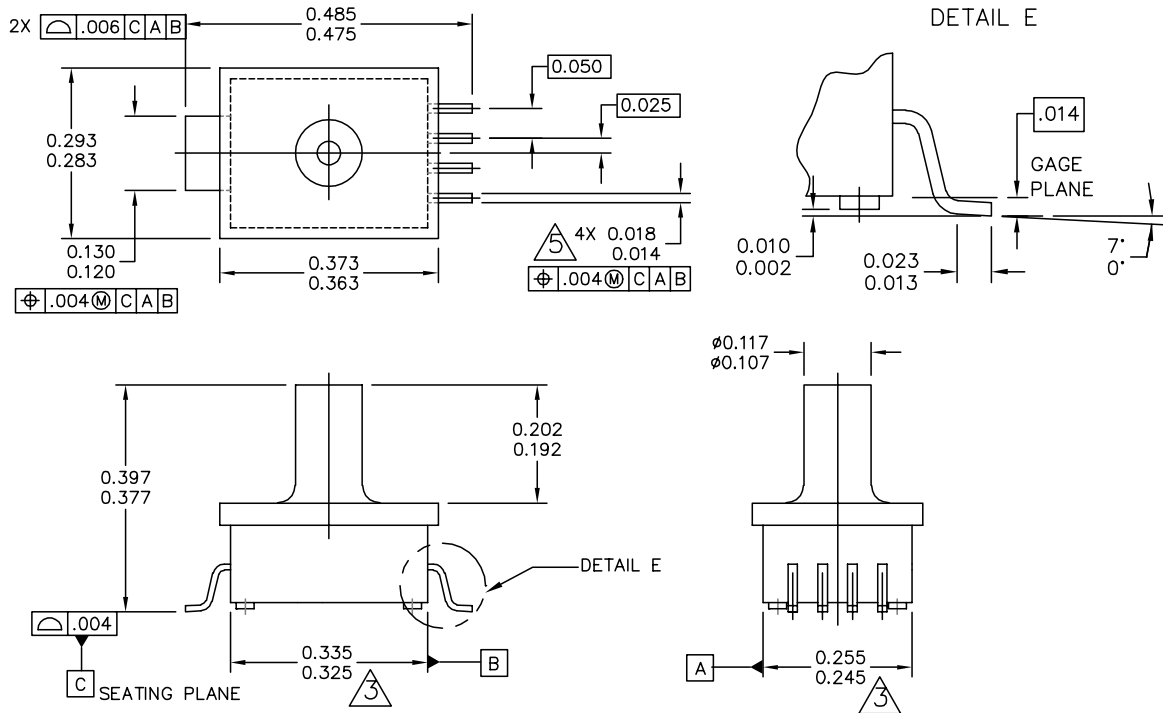


Figure 3. Output versus Pressure Differential

PACKAGE DIMENSIONS



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**CASE 1320A-02
ISSUE A**

MPM22202

PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONS ARE IN INCHES.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.

4. ALL VERTICAL SURFACES TO BE 5" MAXIMUM.

5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

| | | |
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**CASE 1320A-02
ISSUE A**

How to Reach Us:

Home Page:

www.freescale.com

E-mail:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:

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